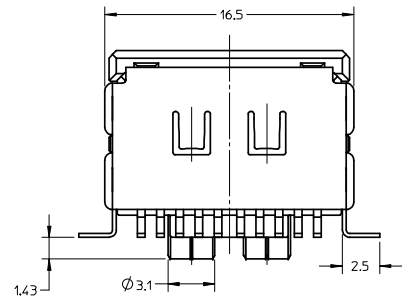
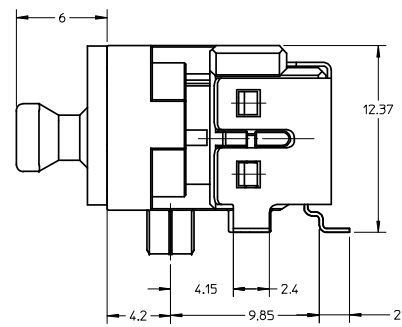
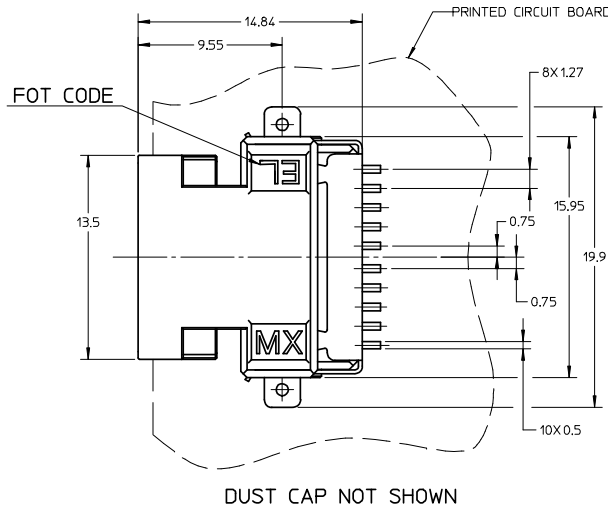
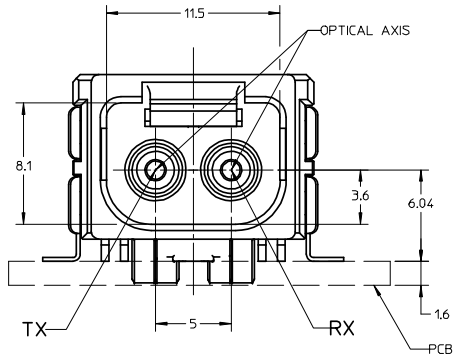
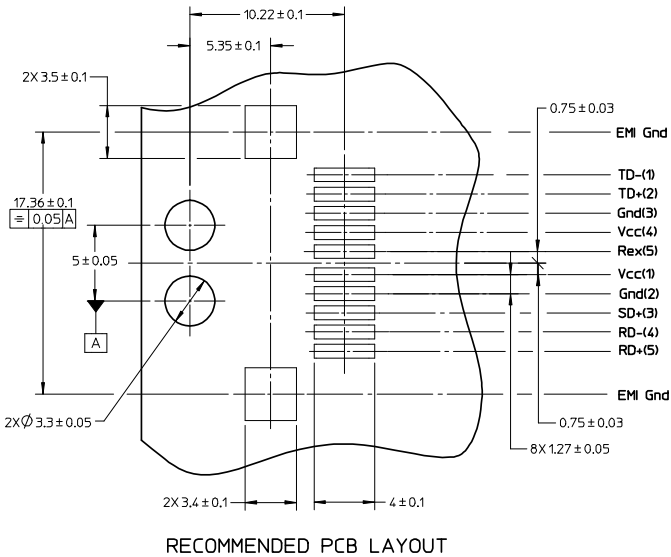
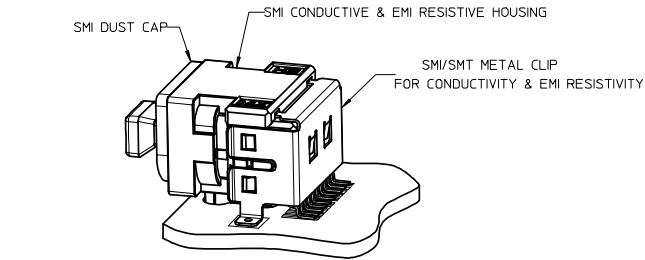
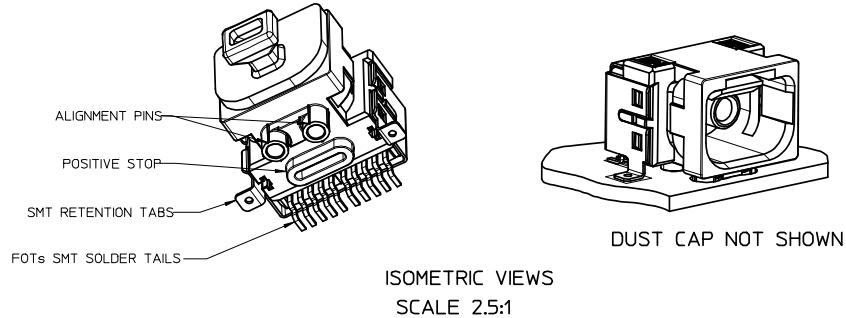


SMI/SMT TRANSCEIVER ASSEMBLY P/N	FOT's TYPE	FOT CODE
1061082200	IEEE-1394/ DIGITAL FDL300K	IE
1061083200	10/100 ETHERNET EDL300K	EL
1061084200	INDUSTRIAL DATA LINK IDL300K	ID



NOTE:
1. ALL DIMENSIONS ARE FOR REFERENCE ONLY EXCEPT FOR RECOMMENDED PCB LAYOUT.
2. ATTACHMENT OF THE COMPONENT TO THE PCB SHALL BE VIA HOT BAR, LASER OR IR SOLDERING.
RE-FLOW OVEN SOLDERING IS NOT APPROVED AT THIS TIME.

ENTER DESCRIPTION EC NO: MF2008-0555 DRWN:SM IGO 2008/06/11 CHKD: 2008/06/11 APPR:SM IGO 2008/06/26 REV: B	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		4:1	METRIC			
			mm	INCH	DRAWN BY DATE		TITLE SMI TRANSCEIVER ASSEMBLY SURFACE MOUNT SOLDERING			
		4 PLACES	± ---	± ---	BG	09/12/06				
		3 PLACES	± ---	± ---	CHECKED BY DATE		MOLEX MOLEX INCORPORATED			
		2 PLACES	± ---	± ---	SE	9/15/06				
		1 PLACE	± ---	± ---	APPROVED BY DATE		DOCUMENT NO. SD-106108-X200 SHEET NO. 1 OF 1			
		ANGULAR ±1/2°			MATERIAL NO.					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE					
		SIZE C					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			